

WRA-32830 - Application No. 09/817,573  
Response to Office action 1/24/2007  
Prel. Amdt. submitted March 26, 2007

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**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended). A method of producing a wafer product, which comprises:

outputting a first wafer sheet with a sugar content of at least 23% or an equivalent content of a sugar substitute from a baking oven;

applying a layer of a food product to the first wafer sheet;

providing a second wafer sheet with a sugar content of at least 23% or an equivalent content of a sugar substitute, and placing the second wafer sheet on the first wafer sheet; and

subsequently compressing the first and second wafer sheets with the layer of food product therebetween and subsequently shaping the first and second wafer sheets containing the layer of the food product while the first and second wafer sheets are maintained in a warm state sufficient to have an elasticity enabling said first and second wafer sheets to be shaped.

Claim 2 (previously amended). The method according to claim 1, which comprises placing onto the first wafer sheet the food product selected from the group consisting

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of a confection, meat product, fish product, cheese product, fruit product, vegetable product, nuts, and almonds.

Claim 3 (previously amended). The method according to claim 1, wherein the sugar substitute is trehalose.

Claim 4 (original). The method according to claim 1, which comprises cutting the pressed-together wafer sheets into individual hollow bodies and subsequently introducing a filling into the hollow bodies.

Claim 5 (previously amended). The method according to claim 1, which comprises, subsequent to the pressing step, cutting the shaped wafer product into individual wafer products and providing the individual wafer products with an outer coating.

Claim 6 (currently amended). The method according to claim 1, which comprises processing, together with the first and second wafer sheets, additional wafer sheets each in a warm state sufficient to have an elasticity enabling said wafer sheets to be shaped with interposed layers of food products.

Claims 7 (withdrawn – currently amended). An assembly for producing wafer products according to claim 1, comprising:

an a baking oven outputting hot wafer sheets;

a conveyor device adjacent said baking oven;

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a lifting device for lifting a respective first wafer sheet of a pair of hot wafer sheets from said conveyor device;

a dosing device for depositing a food product onto a respective second wafer sheet of the pair of hot wafer sheets; and

a processing device disposed to receive the pair of hot wafer sheets for pressing and shaping the two superimposed hot wafer sheets containing the layer of food product.

Claim 8 (withdrawn). The assembly according to claim 7, wherein said baking oven is an automatically controlled baking oven.

Claim 9 (withdrawn). The assembly according to claim 7, wherein said processing device is a shaping device.

Claim 10 (withdrawn). The assembly according to claim 7, wherein said processing device is a suction device.

Claim 11 (withdrawn). The assembly according to claim 7, which further comprises a separation device configured to divide the combined wafer sheets into individual hollow elements.

Claim 12 (withdrawn). The assembly according to claim 11, wherein said separation device is a stamping device.

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Claim 13 (withdrawn). A wafer product, comprising a plurality of wafer sheets and intermediate layers of a food product disposed between respective said wafer sheets, combined by pressing and spatially shaped into individual wafer product.